



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260821000.2	PCN Issued	August 24, 2026
Qualification of SMFAB and AIZU using qualified process technology for select devices		Sample request deadline:	October 23, 2026
		Estimated 1st ship date:	February 20, 2027
Sample requests received after October 23, 2026 will not be supported.			

Change Type(s)	Packing/Shipping/Labeling Wafer Fab Site
ZVEI ID	SEM-PW-02, SEM-PW-13

PCN Details

Description of Change:					
Texas Instruments is pleased to announce the addition of SMFAB and AIZU using the LBC9 qualified process technology for the devices listed below.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
RFAB	LBC9	300mm	SMFAB	LBC9	300mm
RFAB	LBC9	300mm	AIZU	LBC9	200mm
Qual details are provided in the Qual Data Section.					
Reason for Change:		Supply continuity.			

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Review the Standard Data Packet for more details on the changes.								
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><th>RoHS</th><th>REACH</th><th>Green Status</th><th>IEC 62474</th></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change
RoHS	REACH	Green Status	IEC 62474						
☒ No Change	☒ No Change	☒ No Change	☒ No Change						
Changes to product identification resulting from this PCN:	<table><tr><th colspan="4">Fab Site Information</th></tr><tr><td>Chip Site</td><td>Chip Site Origin Code (20L)</td><td>Chip Site Country Code (21L)</td><td>Chip Site City</td></tr></table>	Fab Site Information				Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
Fab Site Information									
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City						

	RFAB	RFB	USA	Richardson
	SMFAB	SHE	USA	Sherman
	AIZU	CU2	JPN	Aizuwakama tsu-shi

Sample product shipping label (not actual product label):

Products Affected:			
DRV6584QPHDRQ1	SN2208035PHDRQ1	TAS6584QPHDRQ1	TAS6584QPHDRQ1
TAS6584SQPHDRQ1			

Approve Date 10-August-2026

Product Attributes

Attributes	Qual Device: <u>TAS6584QPHDRQ1</u>	QBS Package Reference: <u>TAS6584QPHDRQ1</u>	QBS Process Reference: <u>TPS92520QDADRQ1</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Power Management
Wafer Fab Supplier	SMFAB	RFAB	SMFAB
Assembly Site	TAI	TAI	MLA
Package Group	QFP	QFP	TSSOP
Package Designator	PHD	PHD	DAD
Pin Count	64	64	32

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TAS6584QPHDRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>TAS6584QPHDQ1</u>	QBS Package Reference: <u>TAS6584QPHDRQ1</u>	QBS Process Reference: <u>TPS92520QDADRQ1</u>
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	No Fails	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	3/15/0	1/5/0
PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	-	1/45/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests										
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	3/231/0	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	-	-	3/231/0
Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>TAS6584QPHDQ1</u>	QBS Package Reference: <u>TAS6584QPHDRQ1</u>	QBS Process Reference: <u>TPS92520QDADRQ1</u>
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0 ¹
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	1/15/0	1/15/0	1/15
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>TAS6584QPHDQ1</u>	QBS Package Reference: <u>TAS6584QPHDRQ1</u>	QBS Process Reference: <u>TPS92520QPADRQ1</u>
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	1/6/0	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	1/30/0	3/90/0
Additional Tests										

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-067

Approve Date 21-August-2026

Product Attributes

Attributes	Qual Device: <u>TAS6584QPHDRQ1</u>	QBS Package Reference: <u>S0809054C2PAPR</u>	QBS Package Reference: <u>TPS92664QPHPRQ1</u>	QBS Package Reference: <u>TAS6584QPHDRQ1</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 150	-40 to 125	-40 to 125
Product Function	Signal Chain	ASIC	Power Management	Signal Chain
Wafer Fab Supplier	AIZU	CFAB	RFAB	RFAB
Assembly Site	PHI	PHI	PHI	PHI
Package Group	QFP	QFP	QFP	QFP
Package Designator	PHD	PAP	PHP	PHD
Pin Count	64	64	48	64

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TAS6584QPHDRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TAS6584QPHDRQ1	QBS Package Reference: S0809054C2PAPR	QBS Package Reference: TPS92664QPHPRQ1	QBS Package Reference: TAS6584QPHDRQ1
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	No Fails	No Fails	No Fails	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	1/77/0	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	1/77/0	1/77/0	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	1/77/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	-	-
PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	1/45/0	1/45/0	1/45/0	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/135/0	1/45/0	-
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	3/231/0	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	3/2400/0	-	-	-
Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	1/30/0

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WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	-	1/10/0
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LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	-	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	-	-	-
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- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2506-039

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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